

Product/Process Change Notification

N° 2020-070-A

Dear customer,

please find attached our Infineon Technologies AG PCN:

Several changes affecting product TLD1211SJ

Important information for your attention:

- Please respond to this PCN by indicating your decision on the approval form, sign it and return to your sales partner before 2022-01-20.
- Infineon aligns with the widely-recognized JEDEC STANDARD "JESD46", which stipulates: "Lack of acknowledgement of the PCN within 30 days constitutes acceptance of the change." Notwithstanding the aforesaid individual agreements shall prevail.

Your prompt reply will help Infineon to assure a smooth and well-executed transition. If Infineon does not hear from your side by the due date, we will assume your full acceptance to this proposed change and its implementation.

Your attention and response to this matter is greatly appreciated.



On 16 April 2020, Infineon acquired Cypress. We are now in the process of merging and consolidating our tools and processes for PCN, Information Notes, Errata and Product Discontinuance. For further details, please visit our website: <u>https://www.infineon.com/cms/en/about-infineon/company/cypress-acquisition/</u>

Infineon Technologies AG

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Chairman of the Supervisory Board: Dr. Wolfgang Eder

Management Board: Dr. Reinhard Ploss (CEO), Dr. Helmut Gassel, Jochen Hanebeck, Constanze Hufenbecher, Dr. Sven Schneider

Registered Office: Neubiberg

Commercial Register: München HRB 126492



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Products affected	Please refer to attached affected product list 1_cip20070_A		
Detailed change information			
Subiect:	Several changes affecting product TLD1211SJ		
Reason/Motivation:	Due to continuously raising demand for Infineon automotive products exceeding the capacity in location Villach, the wafer production and test for TLD1211SJ is transferred to Kulim. To fulfil our customer volume demands of TLD1211SJ the assembly is transferred from in-house location Melaka to subcon Amkor Technologies Philippines.		

Description		New	
PROCESS - WAFER PRODUCTION: New wafer diameter	150mm	200mm	
PROCESS - WAFER PRODUCTION: Move all or parts of production to a different wafer fab site.	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia	
PROCESS - ASSEMBLY: Change of lead frame finishing material / area (internal)	-	NiPdAu	
PROCESS - ASSEMBLY: Change of lead and heat slug plating material/plating thickness (external)		NiPdAu	
PROCESS - ASSEMBLY: Die attach material		ABLEBOND 8290	
PROCESS - ASSEMBLY: Change of wire bonding	25μm Au	30µm Cu	
PROCESS - ASSEMBLY: Change of mold compound / encapsulation material	CEL 9220	EME G700	
PROCESS - ASSEMBLY: Change of product marking	Package: PG-DSO-8-16 Pin 1 marking with mold tool no backside marking	Package: PG-DSO-8-64 Pin 1 marking with laser backside marking with laser	
PROCESS - ASSEMBLY: Move all or parts of production to a different assembly site.	Infineon Technologies (Advanced Logic) Sdn. Bhd., Melaka, Malaysia	AMKOR Technology Philippines Inc. (ATP), Muntinlupa City, Philippines	



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EQUIPMENT: Production from a new equipment/tool which uses a different basic technology or which due to its unique form or function can be expected to influence the integrity of the final product	Infineon tool park	OSAT tool park		
TEST FLOW: Move of all or part of electrical wafer test and/or final test to a different test site.	Infineon Technologies Austria AG, Villach, Austria	Infineon Technologies (Kulim) Sdn. Bhd., Kulim, Malaysia		
Data sheet update	Rev 1.0	Rev 1.1		
Product identification	Wafer lot numbers from Villach start with VExxxxx. Wafer lot numbers from Kulim with 1Exxxxxx Traceability assured via date code. Marking pattern different for new assembly site. No change in SP ordering number			
Anticipated impact of change	ticipated impact of change Based on the qualification performed, Infineon does not expect an impact on quality, function and reliability. No change in form, fit a expected.			
	DeQuMa-ID(s): SEM-PW-02 / SEM-PW-13 / SEM-PA-04 / SEM-PA-05 / SEM-PA- 07 / SEM-PA-08 / SEM-PA-11 / SEM-PA-13 / SEM-PA-18 / SEM-EQ-01 / SEM-TF-01			
Attachments	1 cip20070 A	affected product list		
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Time schedule				

Time schedule

Final qualification report	available
First samples available	on request
Intended start of delivery [1]	2022-06-15 not applicable for data sheet update (documentation only)
Last order date (LOD) [2]	2022-06-15
Last delivery date (LDD) [3]	2023-06-15

[1] provided date or earlier after customer approval

[2] Last time buy volume to be placed latest until LOD

[3] Delivery of new product can be earlier (see Intended start of delivery) and depends on approval

If you have any questions, please do not hesitate to contact your local sales office.



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Several changes affecting product TLD1211SJ

Sales name	SP number	OPN	Package
TLD1211SJ	SP000735204	TLD1211SJFUMA1	PG-DSO-8-16
TLD1211SJ	SP000735204	TLD1211SJFUMA1	PG-DSO-8-64